

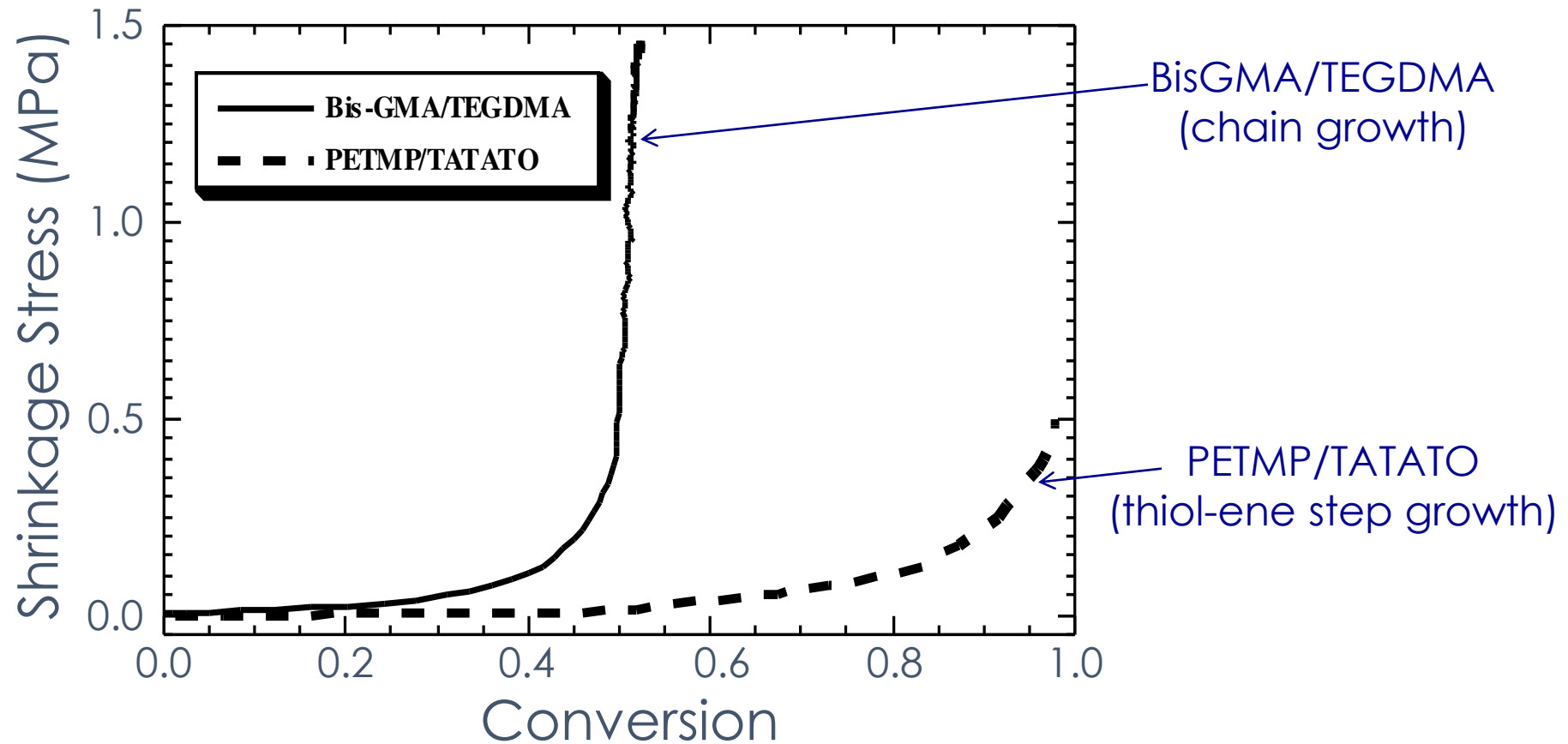
# Connectivity reconfiguration for additive manufacturing

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Department of Materials Science & Engineering  
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# Photopolymerizations Generally Lead to Shrinkage Stress



*Most thermosetting reactions/processes lead to stresses of various amounts*

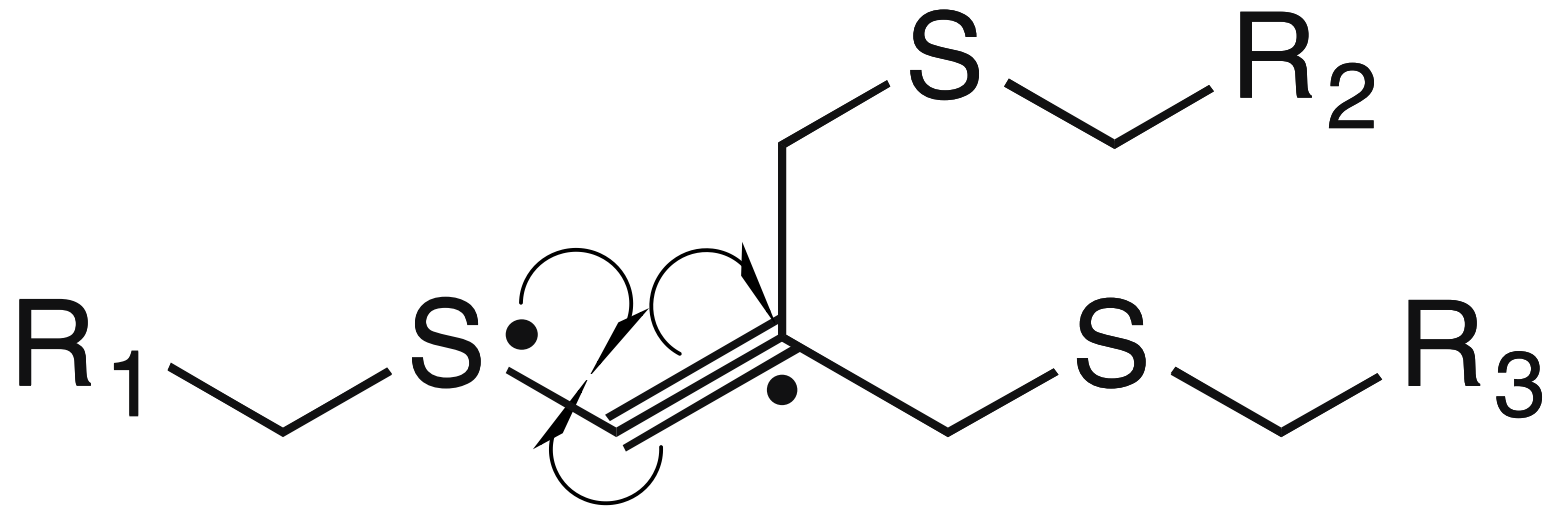
# Solving Shrinkage Stress

- Shape/molecular structure of cross-linked polymers traditionally set, fixing in shrinkage stress
  - *Solution: Incorporate functional groups that reversibly cleave and reform in a controllable manner*

## HOW?

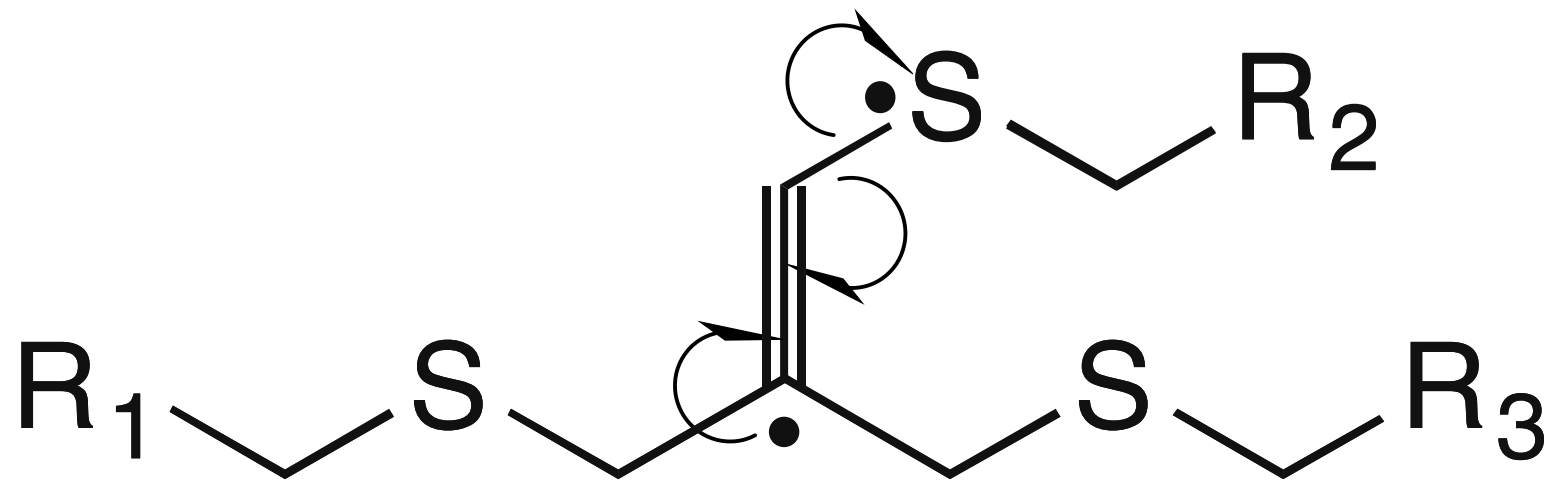
- Select dynamic covalent backbone chemistry that rapidly and reversibly rearranges in the presence of active centers (radicals)
  - *Use light exposure to trigger the radical generation*

# The Allyl Sulfide Functionality: Addition-Fragmentation Chain Transfer (AFCT)



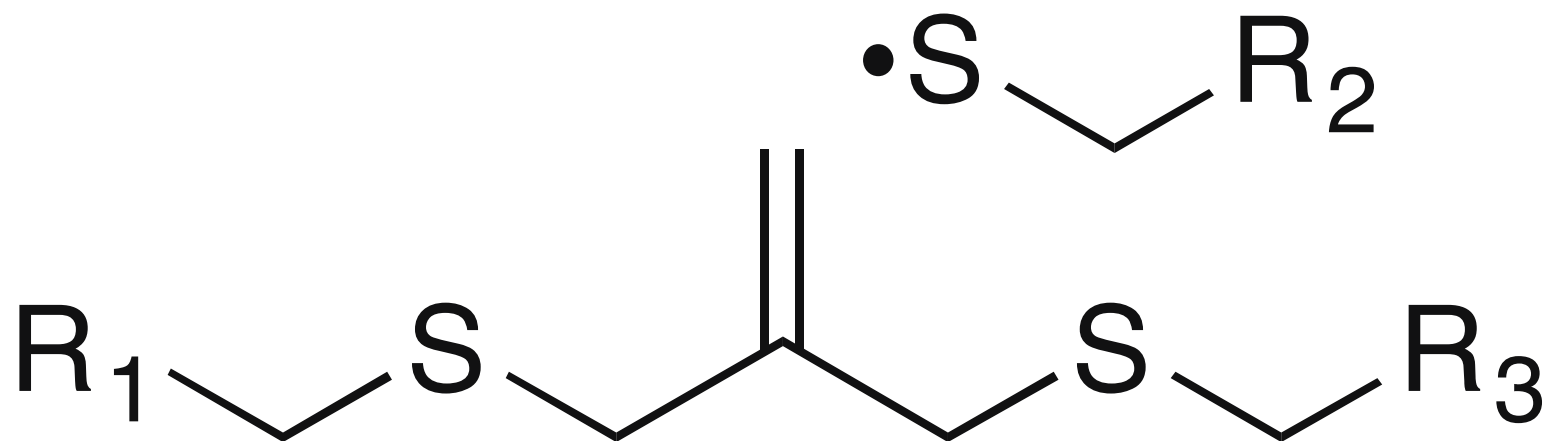
New link or branch made as radical gets to original radical  
reaction with the allyl sulfide

# The Allyl Sulfide Functionality: Addition-Fragmentation Chain Transfer (AFCT)



For the formation of a new radical, the addition and fragmentation of the propagating radical are in a dynamic equilibrium.

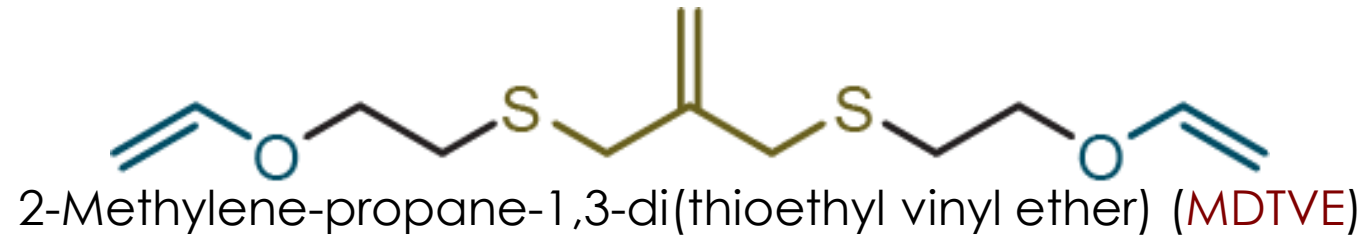
# The Allyl Sulfide Functionality: Addition-Fragmentation Chain Transfer (AFCT)



Formation of a new “near-equilibrium” connection  
and reformation of the propagating radical

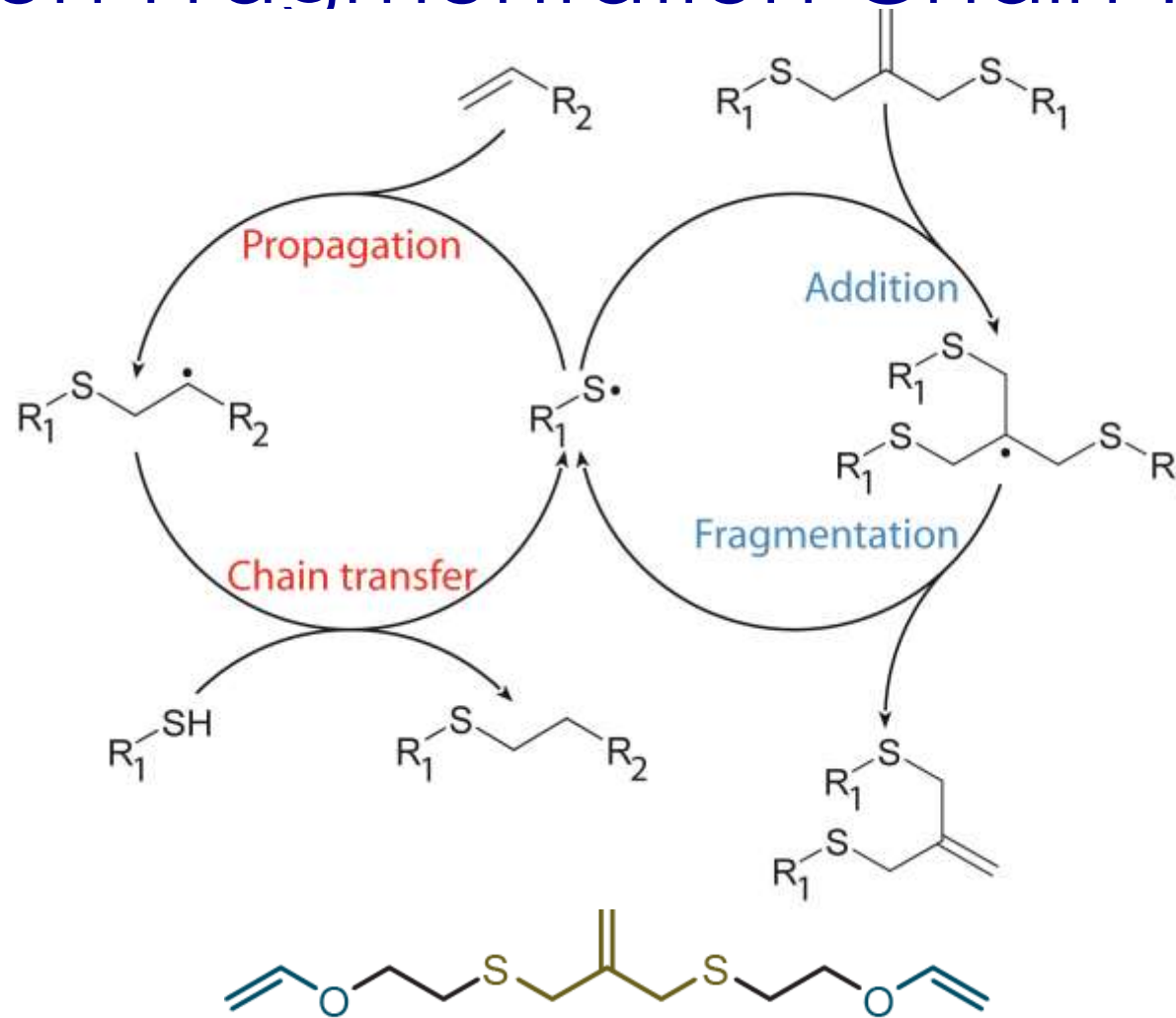
# Hypothesis: Addition-fragmentation allows thiol-ene networks to find a lower energy state.

Reduction of stresses induced during photopolymerization?





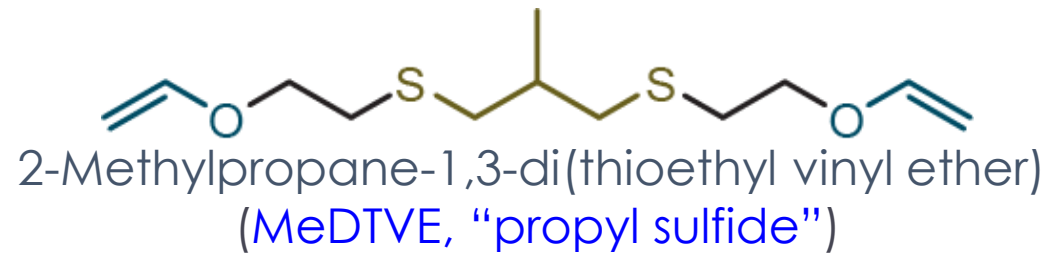
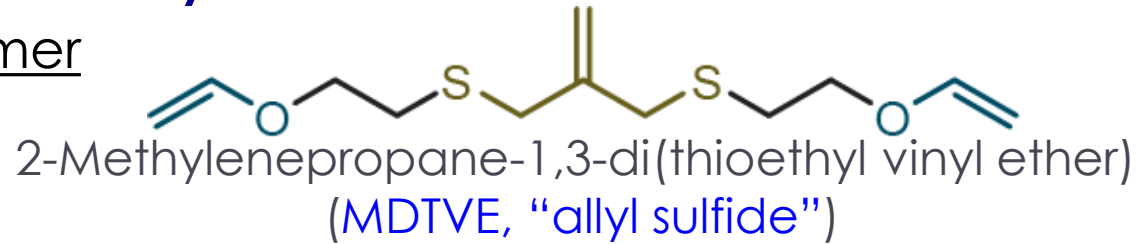
# Concurrent Thiol-Ene Polymerization/ Addition-Fragmentation Chain Transfer



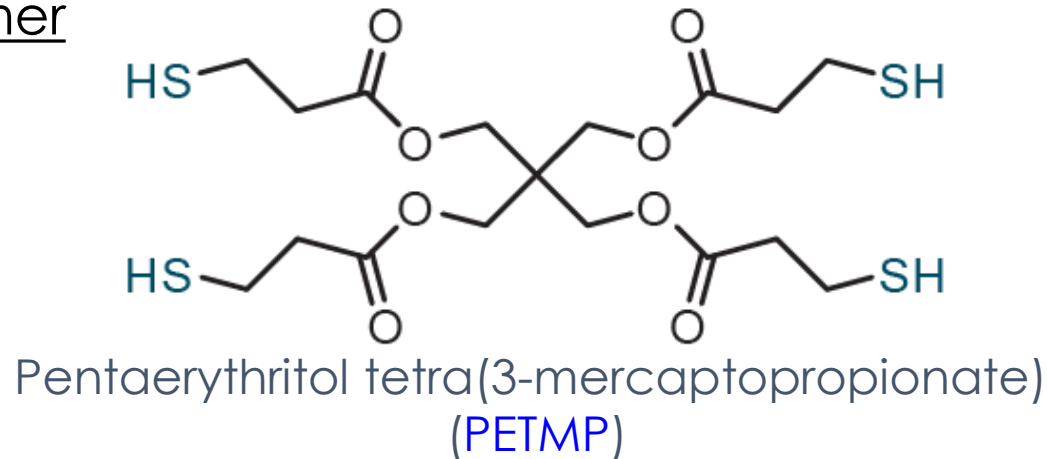


# Incorporation of the Allyl Sulfide AFCT Functionality in a Thiol-Ene Network

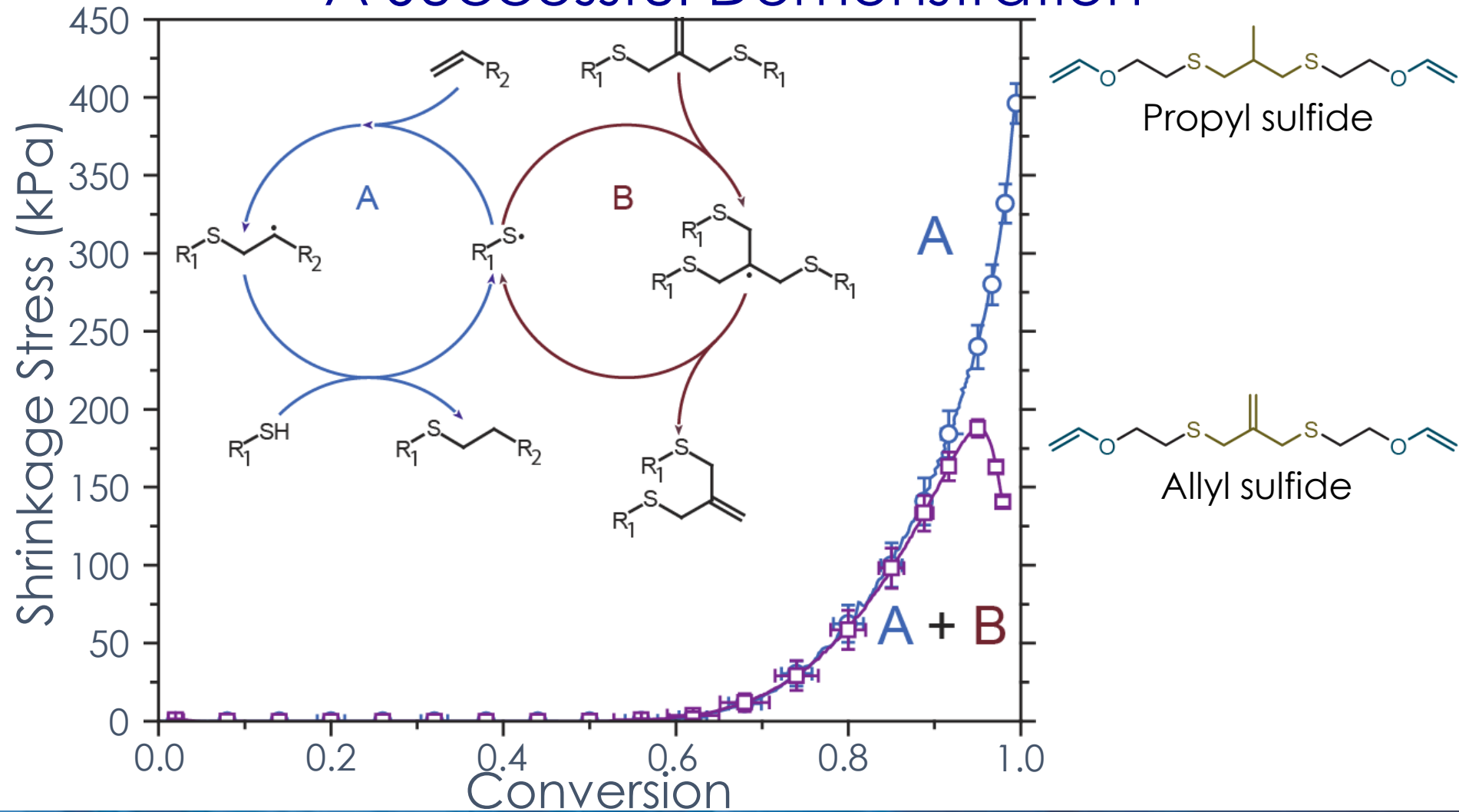
'Ene' monomer



'Thiol' monomer

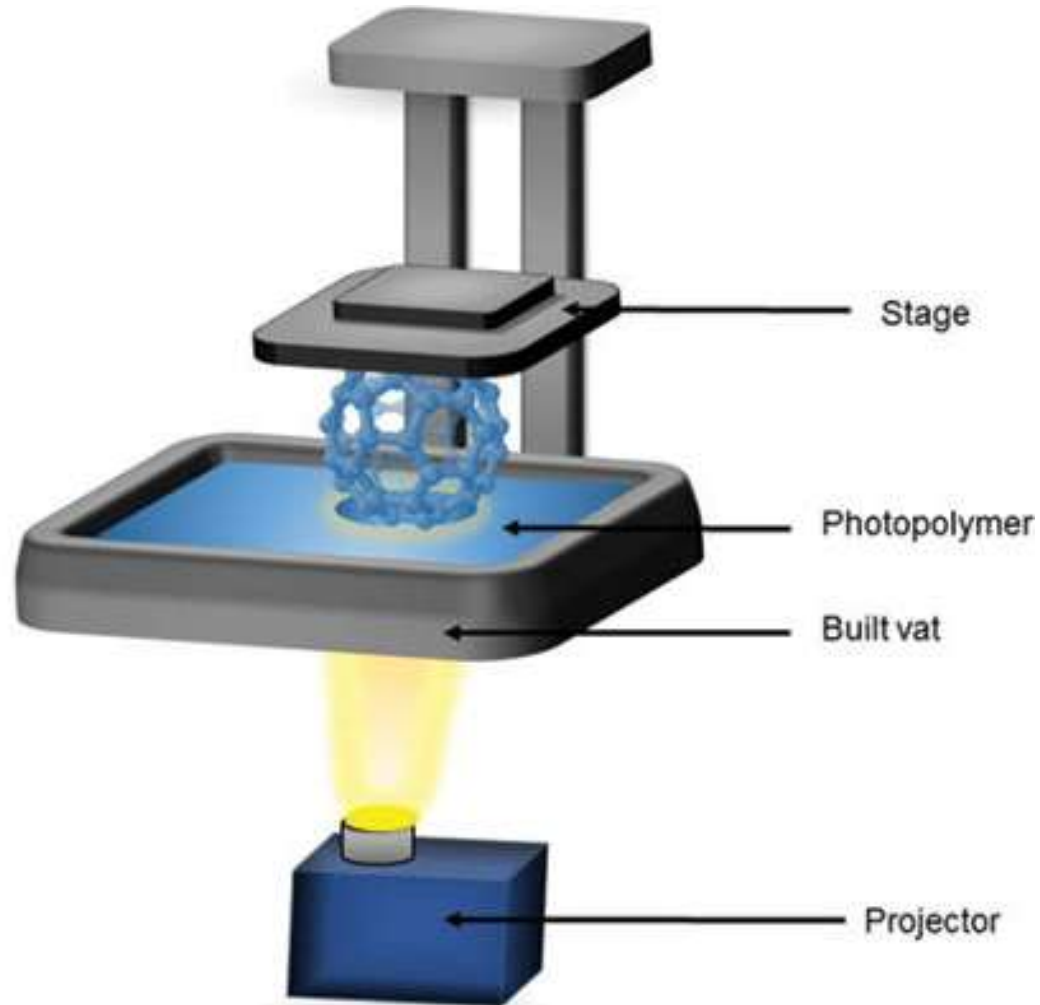


# Stress Relaxation During Photopolymerization: A Successful Demonstration



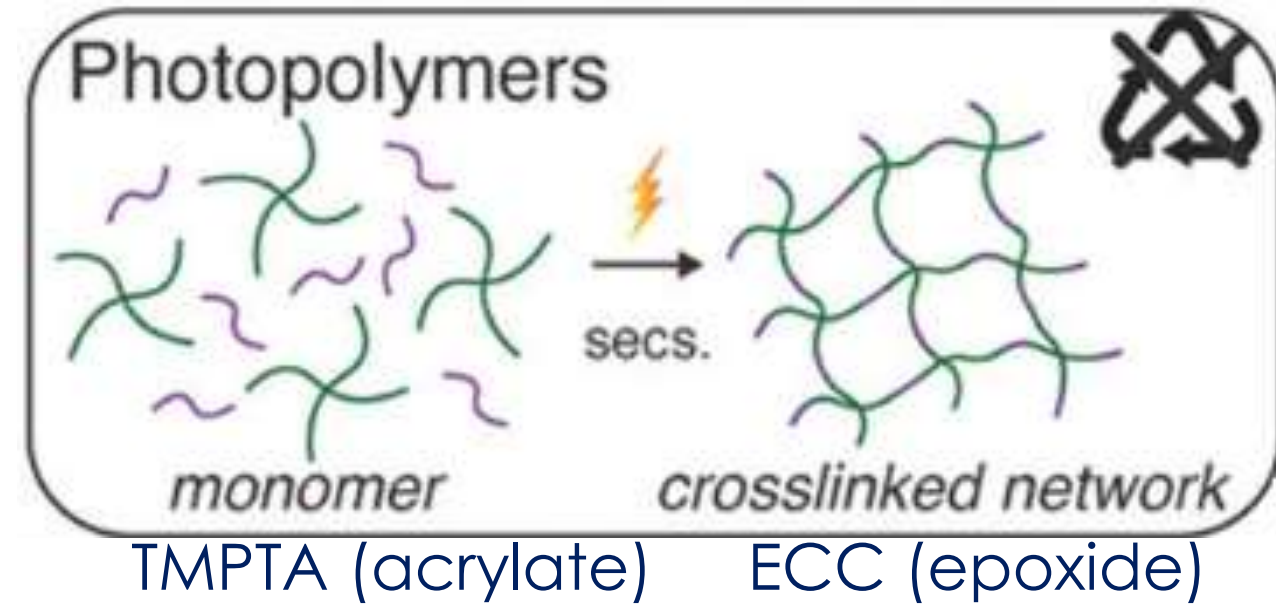
Irradiation: 365 nm, 0.8 wt% HCPK

# Stereolithography (SLA)



Bottom-Up SLA

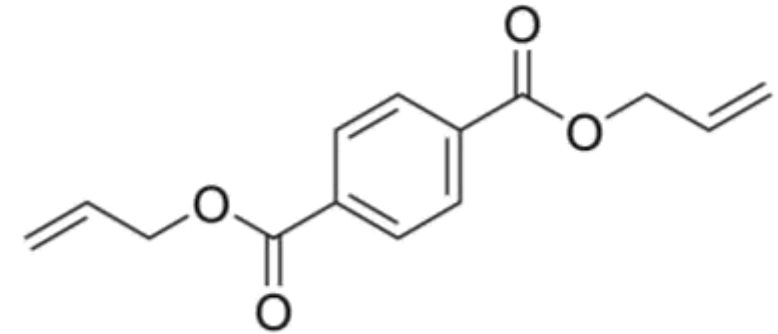
## Photocurable thermosets



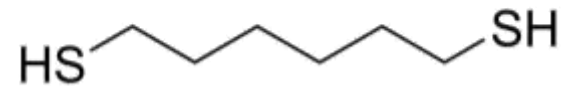
# Thermoplastics in SLA

## Unique challenges

- Photopolymerizable
- Rapid curing rate
- Solid-liquid phase separation



diallyl terephthalate  
(DAT)



1,6 – hexanedithiol

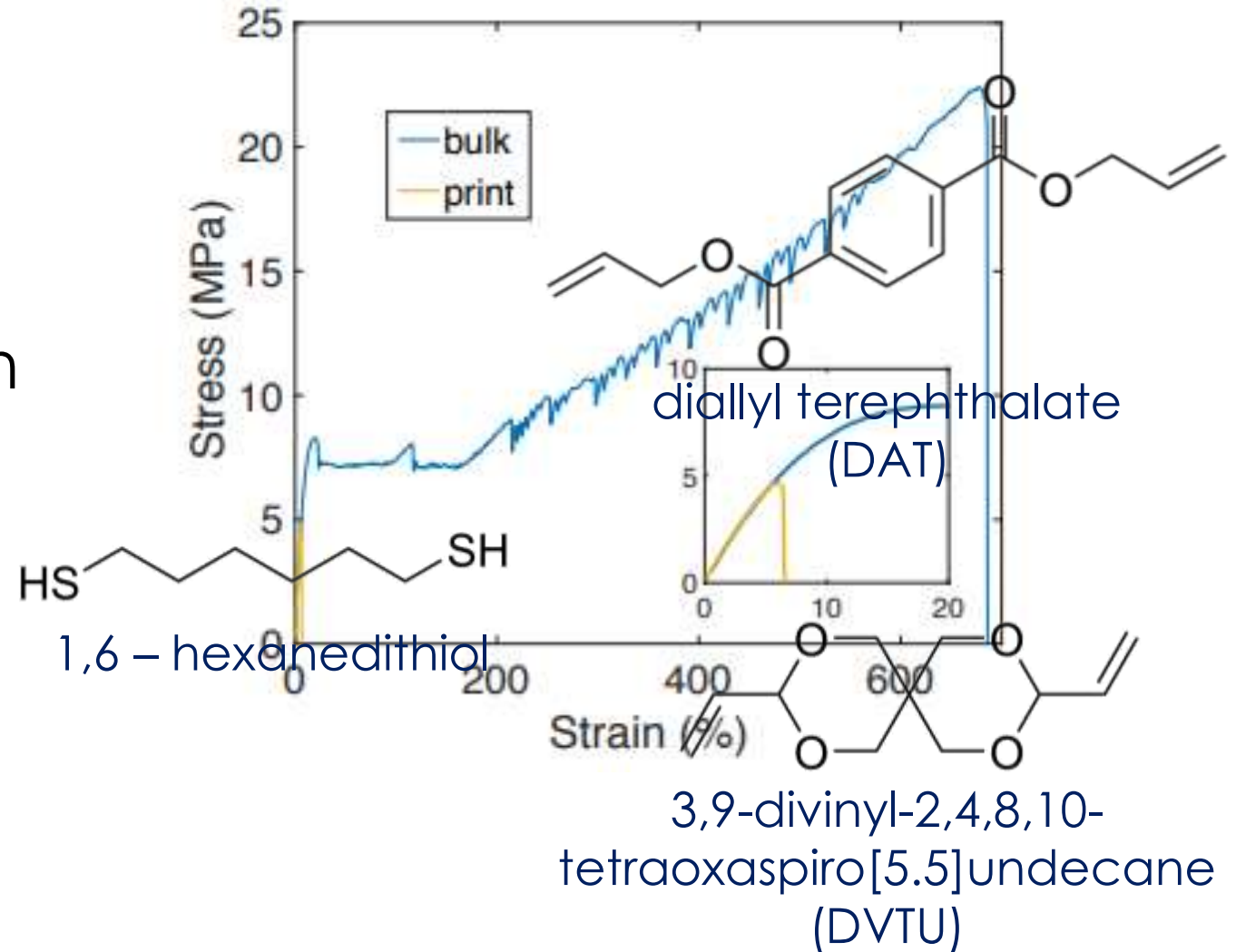


3,9-divinyl-2,4,8,10-  
tetraoxaspiro[5.5]undecane  
(DVTU)

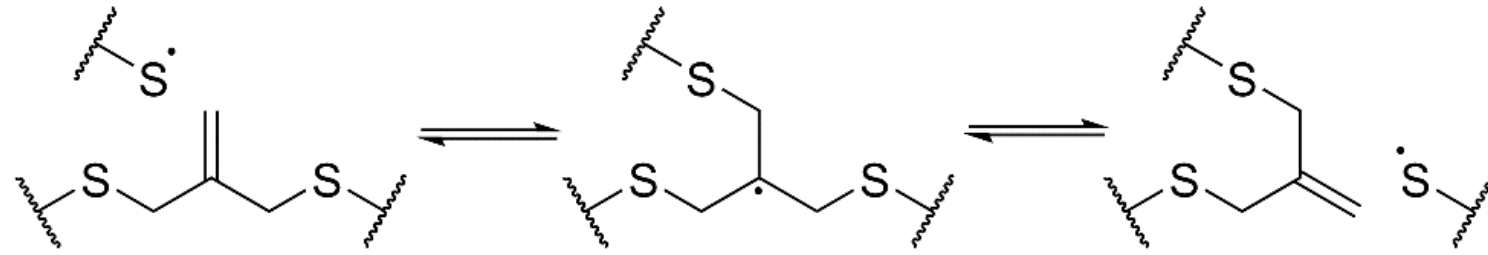
# Thermoplastics in SLA

## Unique new challenges

- Slow crystallization
- Poor interlayer adhesion

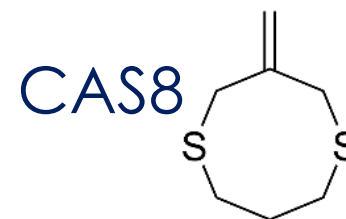
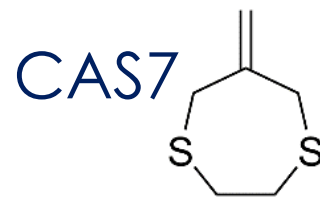
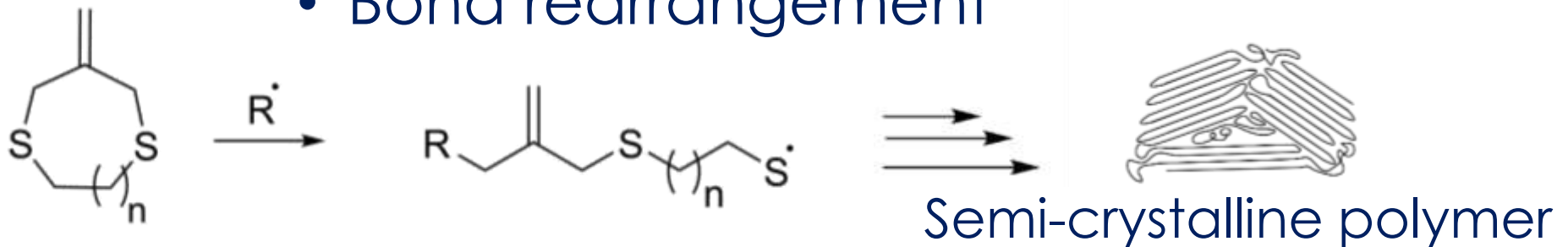


# Addressing Thermoplastic Limitations in SLA



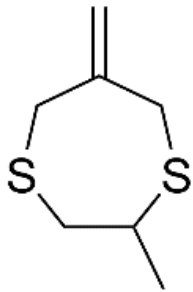
*Addition-fragmentation chain transfer*

- Stress relaxation
- Bond rearrangement

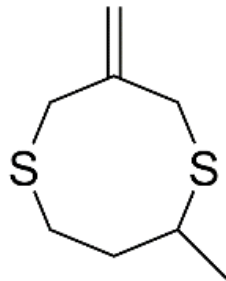




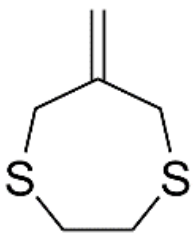
# Photopolymerization Kinetics: DSC



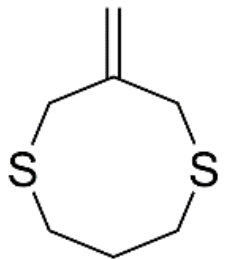
MDTE



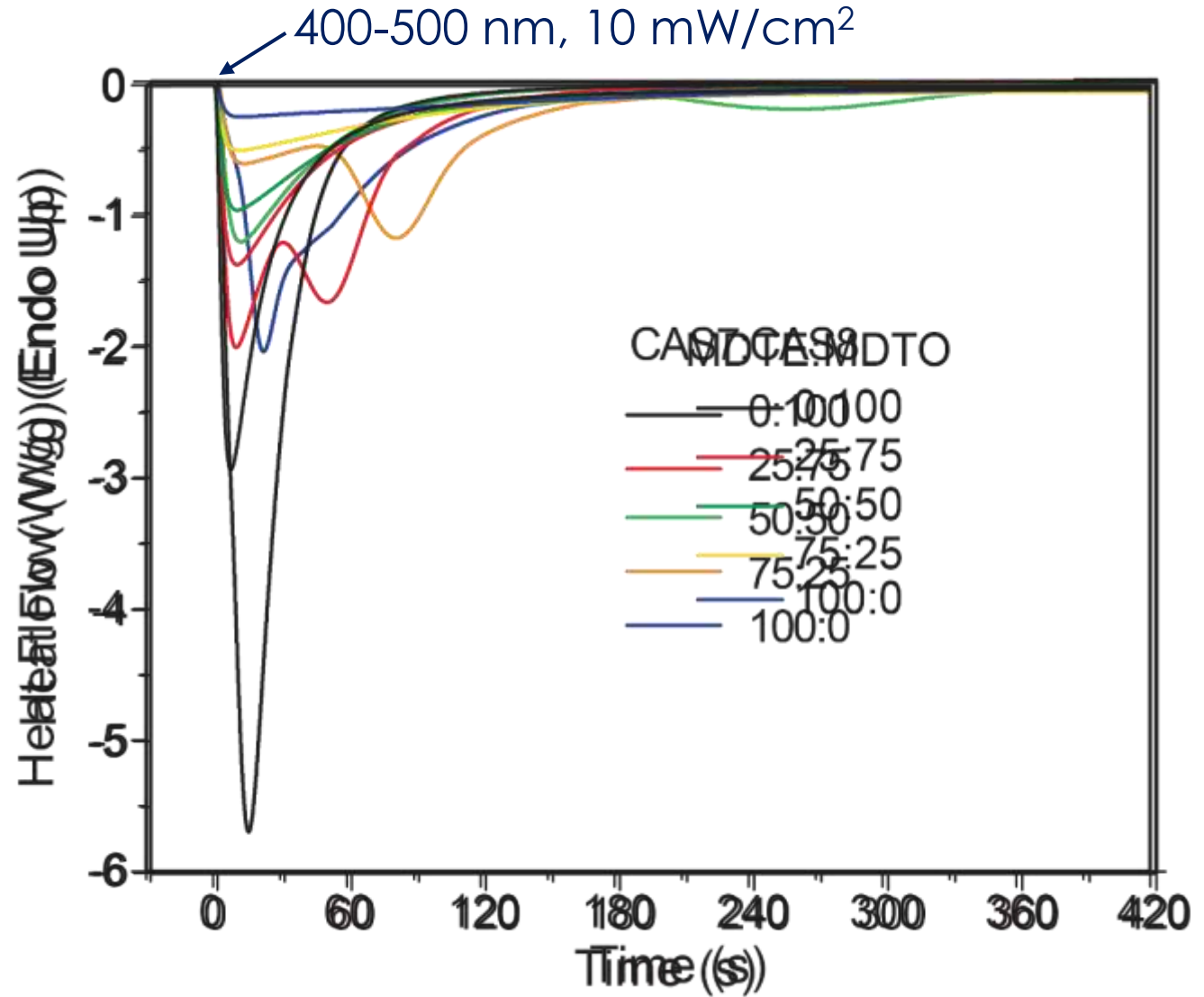
MDTO



CAS7

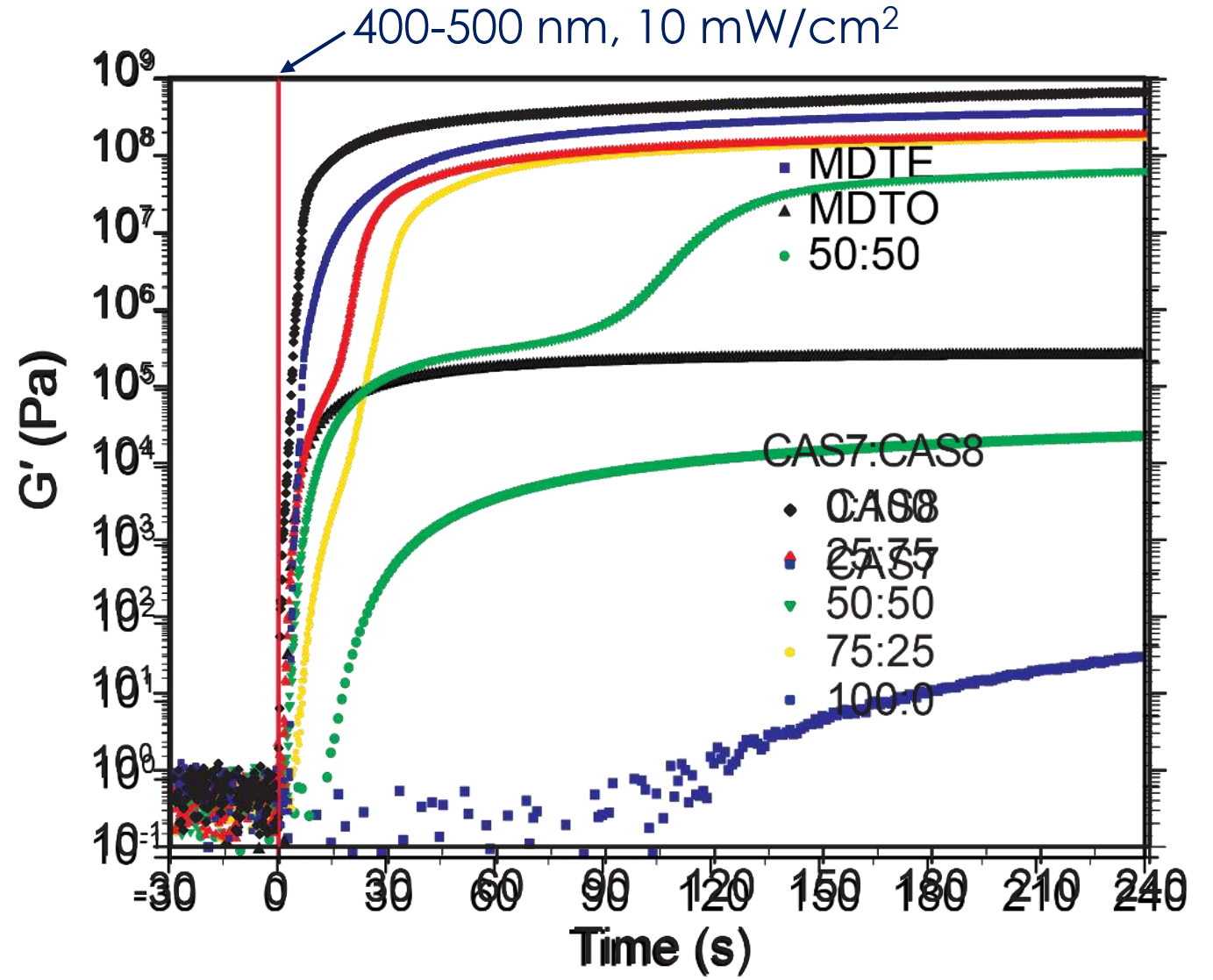
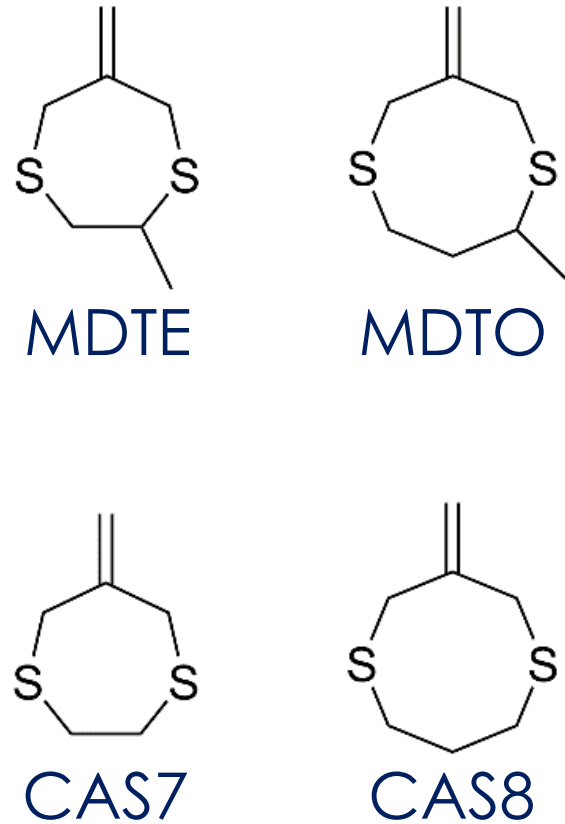


CAS8

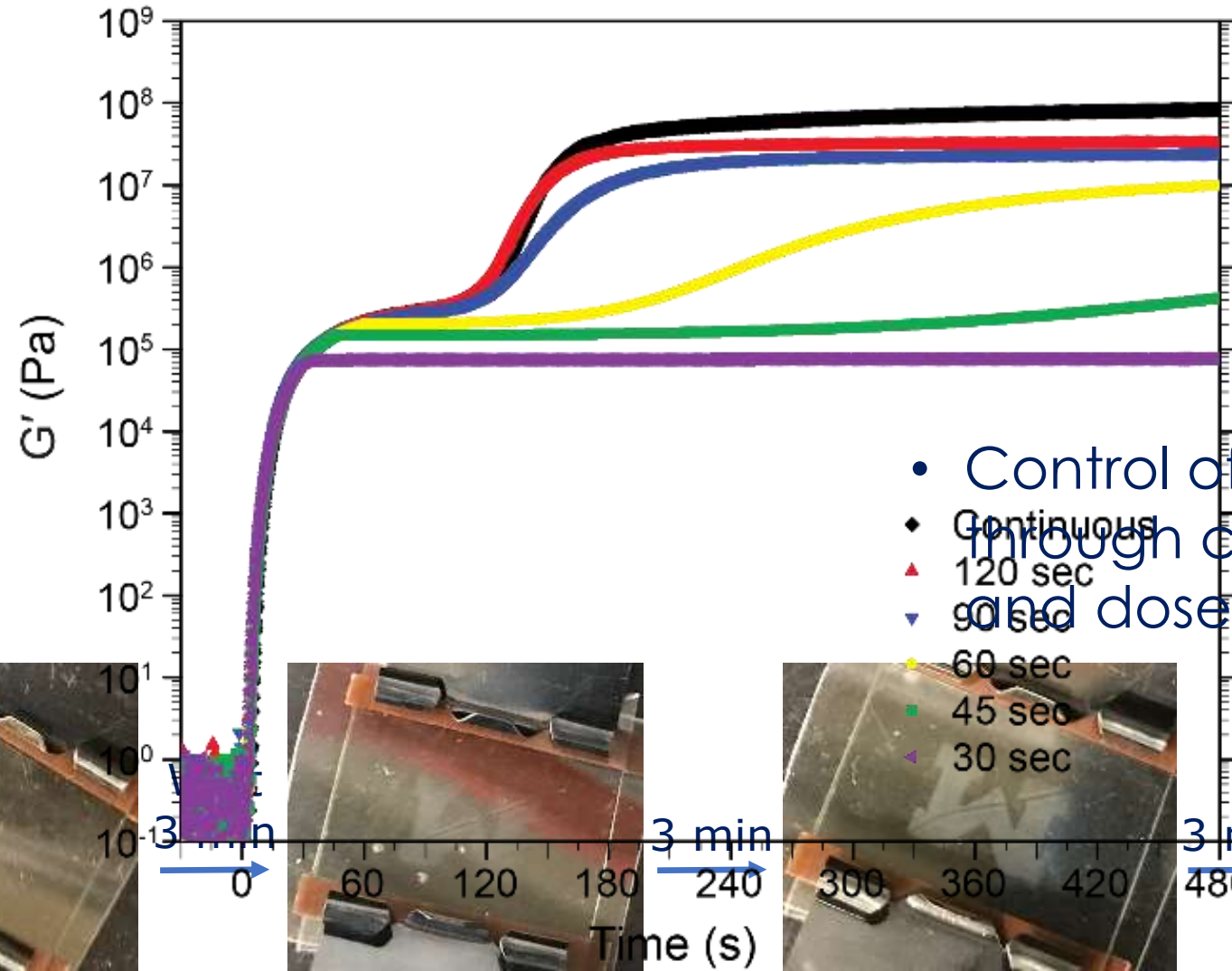
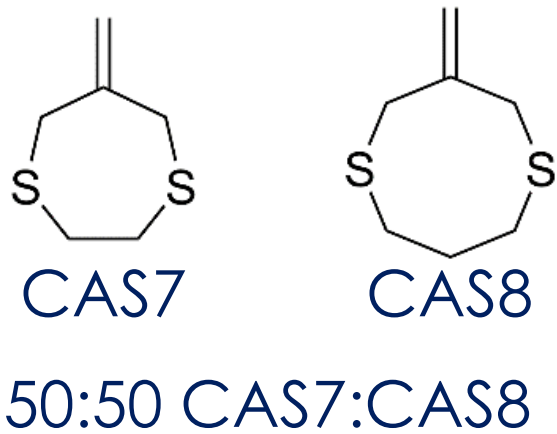




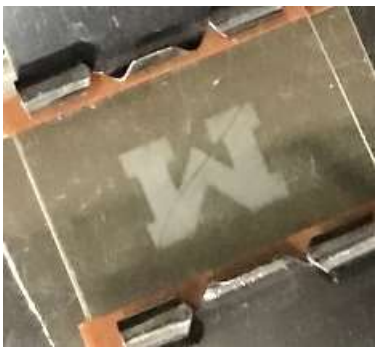
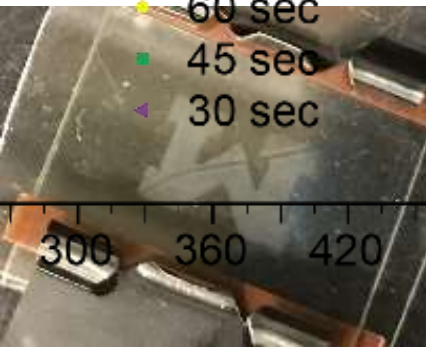
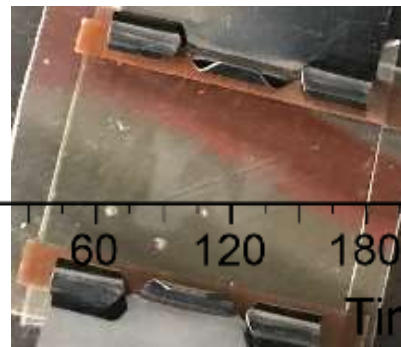
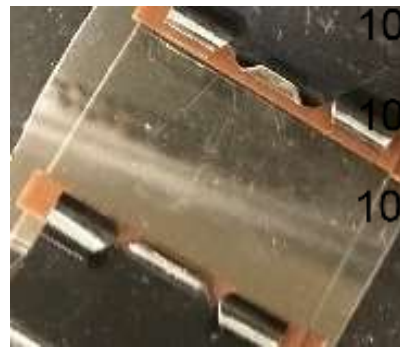
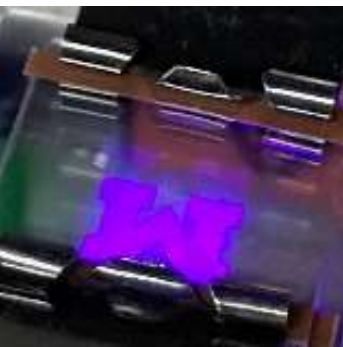
# Photopolymerization Kinetics: Rheometry



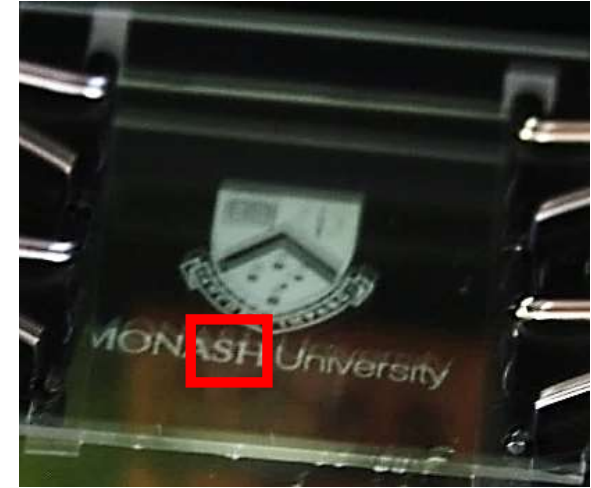
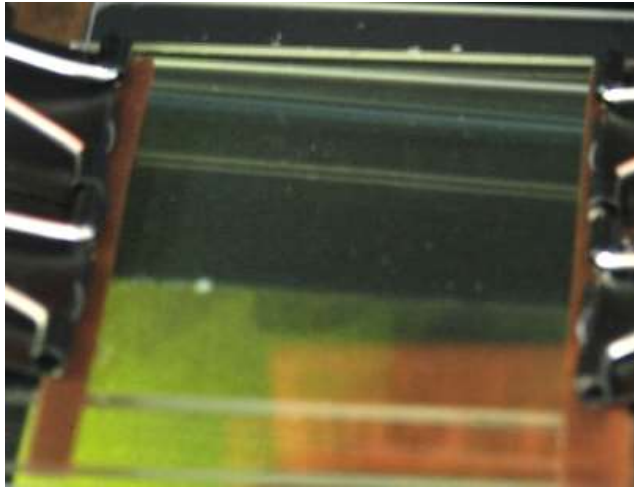
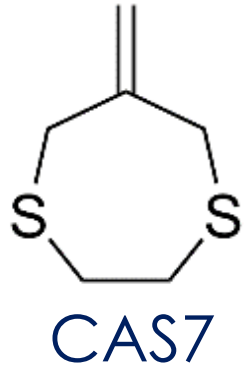
# Dark Crystallization



- Control of crystallization through composition and dose of irradiation
- Continuous
- 120 sec
- 90 sec
- 60 sec
- 45 sec
- 30 sec



# Crystallization Photopatterning



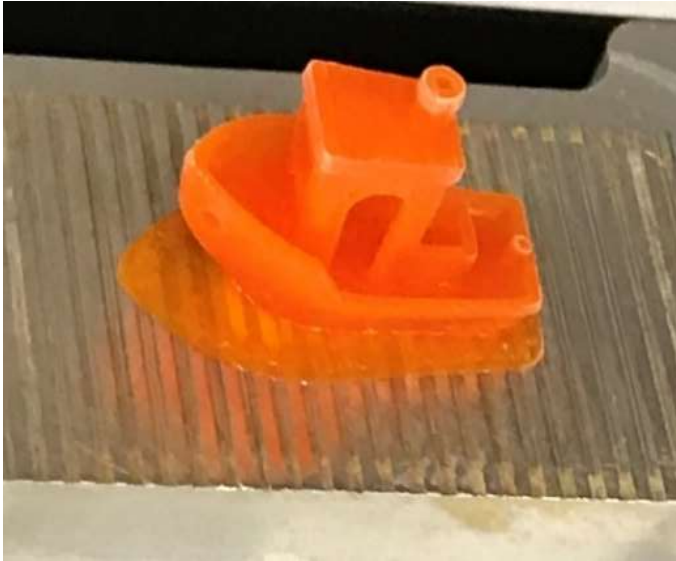
- Crystallization confinement enables layerwise photopatterning



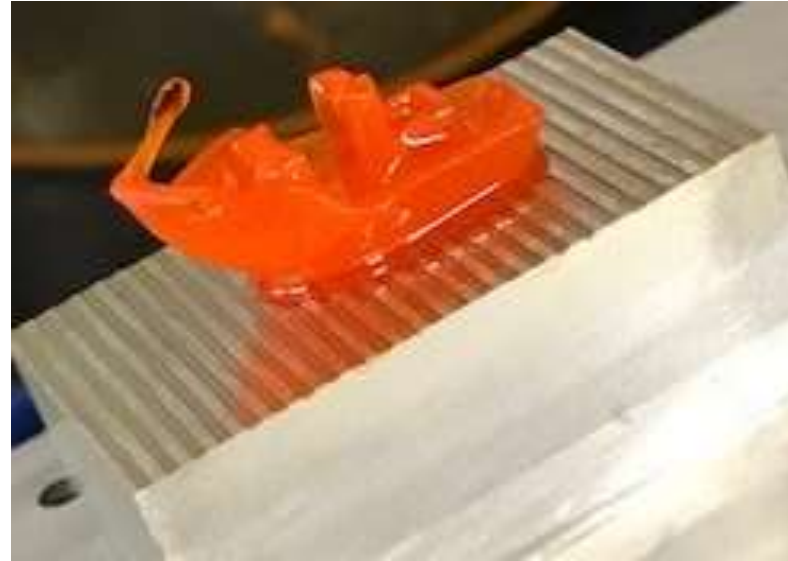


# Stereolithographic Printing

CAS8



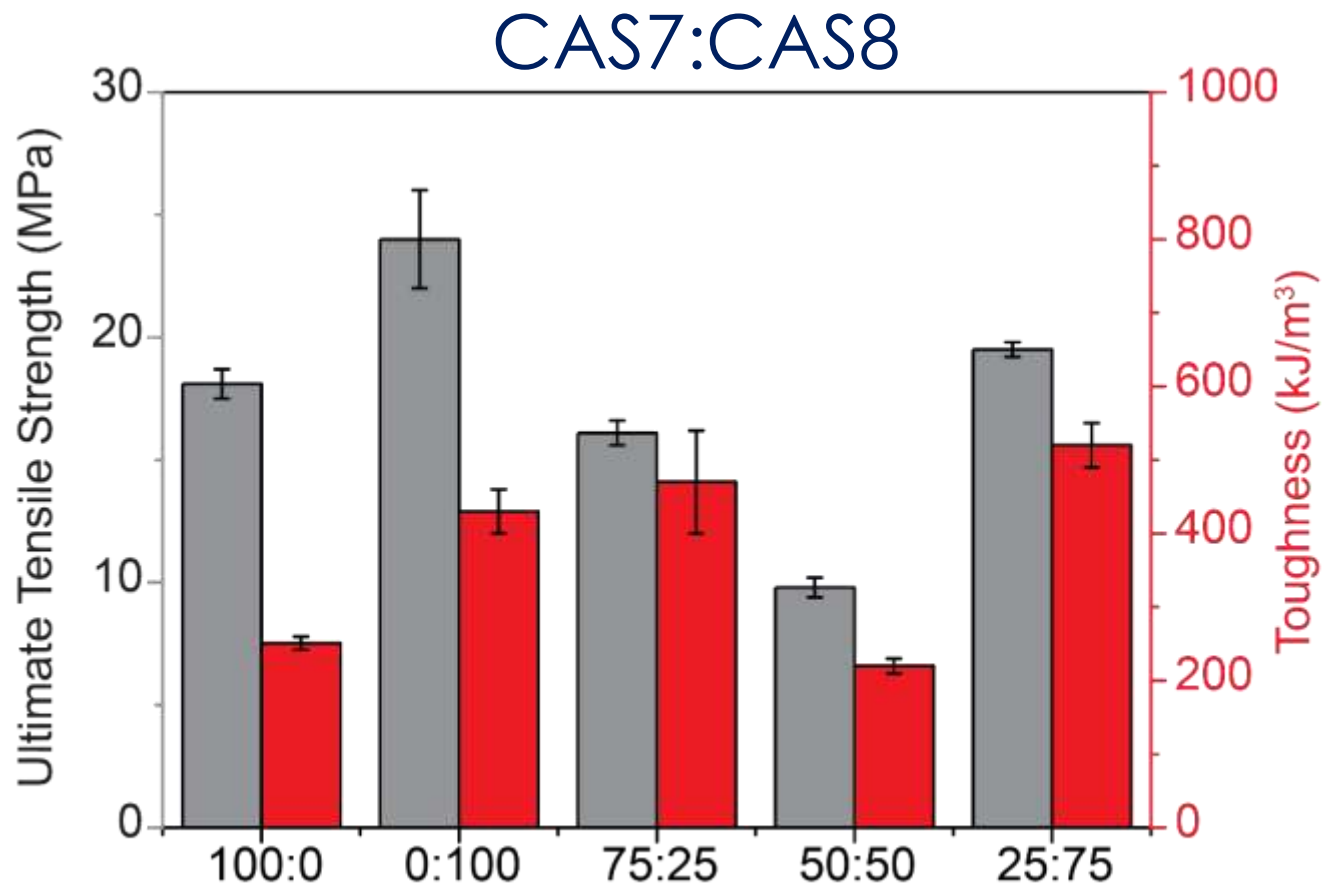
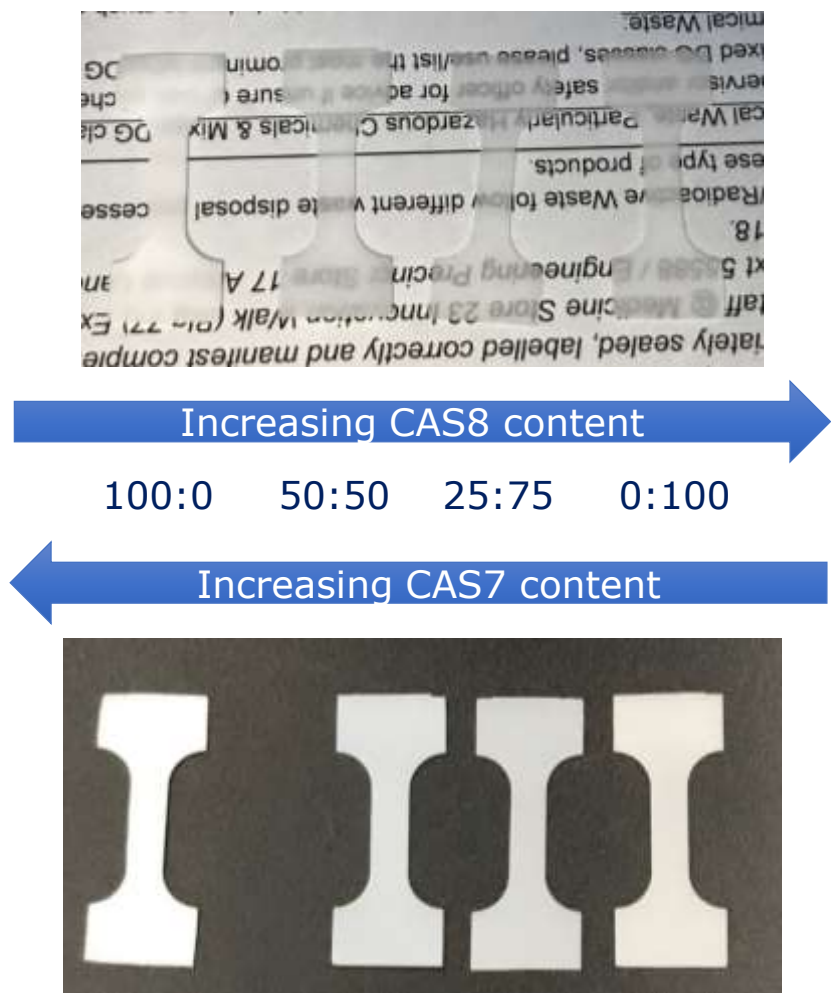
50:50 CAS7:CAS8



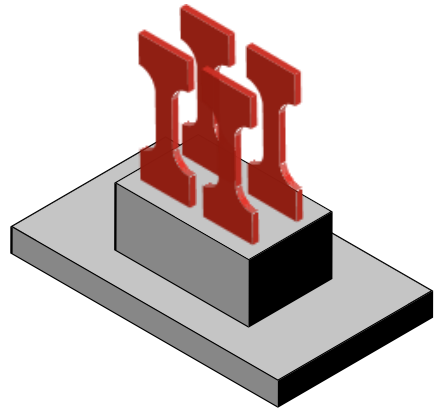
25:75 CAS7:CAS8



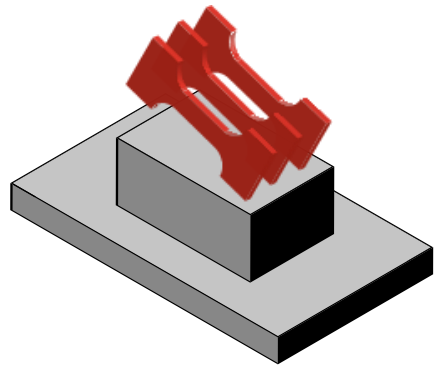
# Bulk Mechanical Properties



# Printed Mechanical Properties



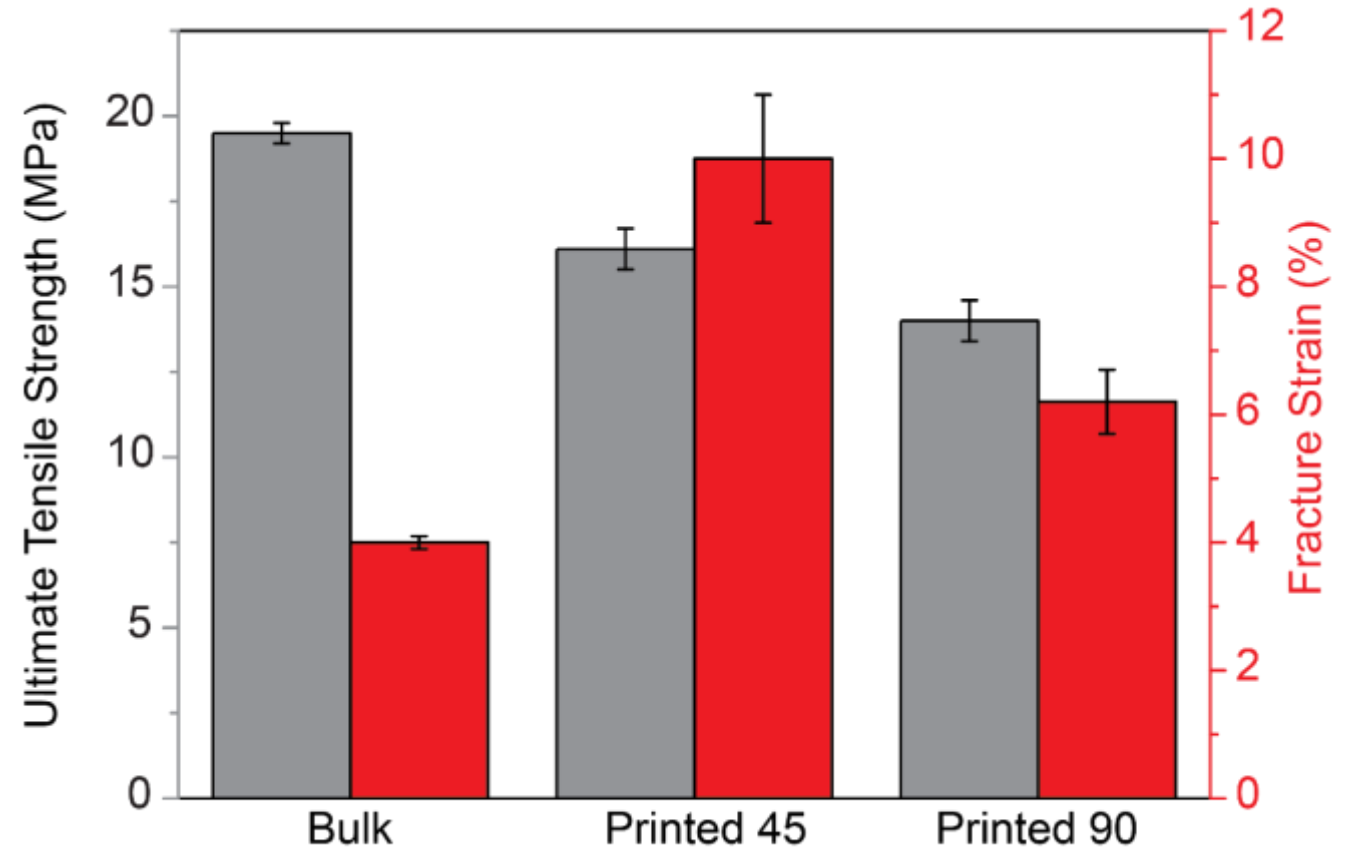
Printed 90°



Printed 45°

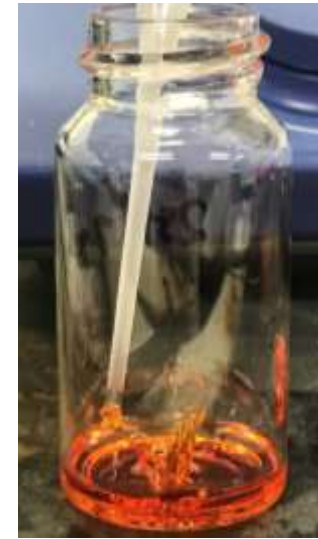
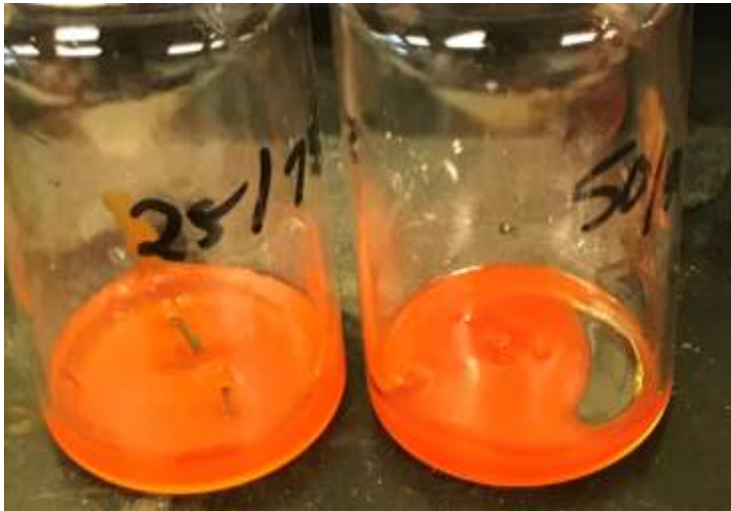
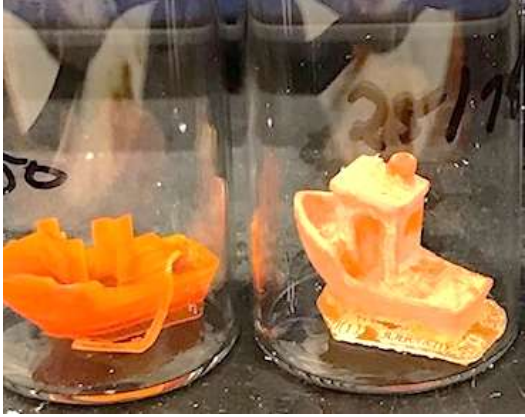


25:75 CAS7:CAS8





# Thermoplastic Melting

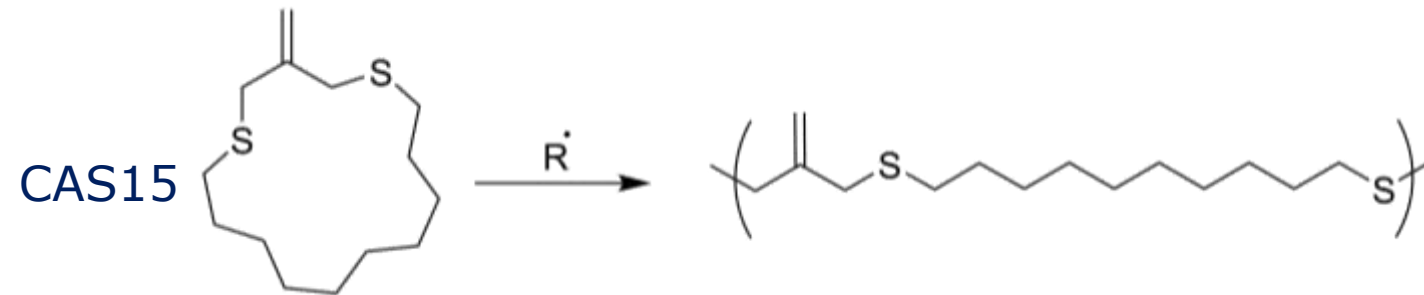
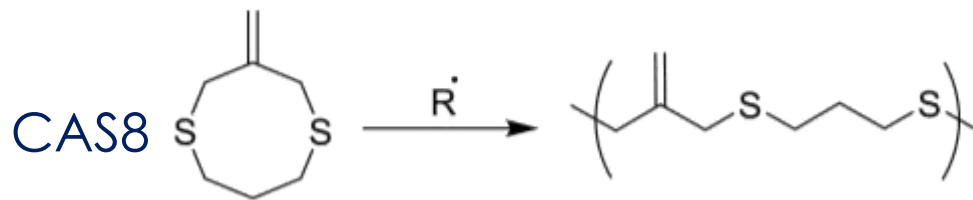
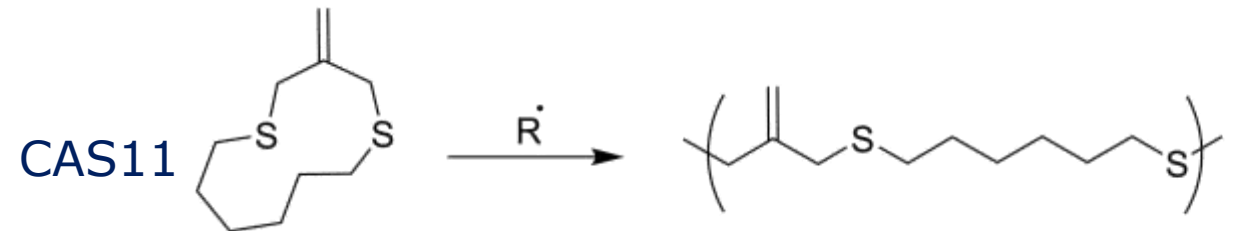
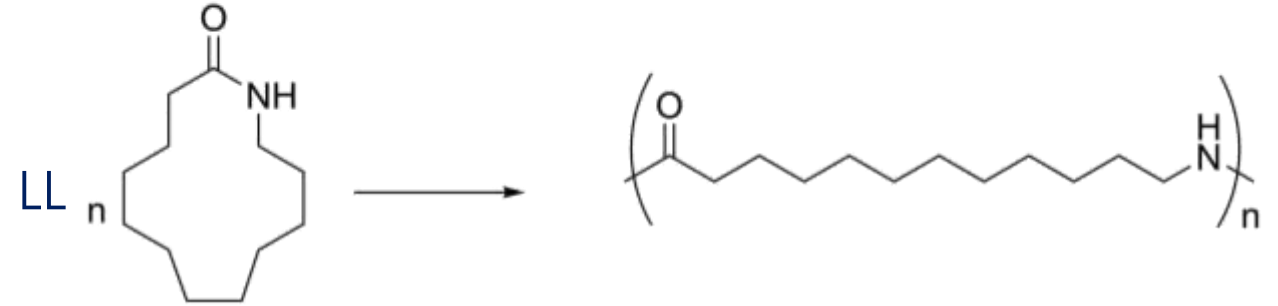
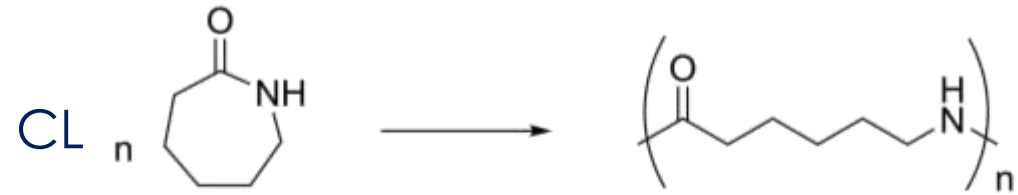




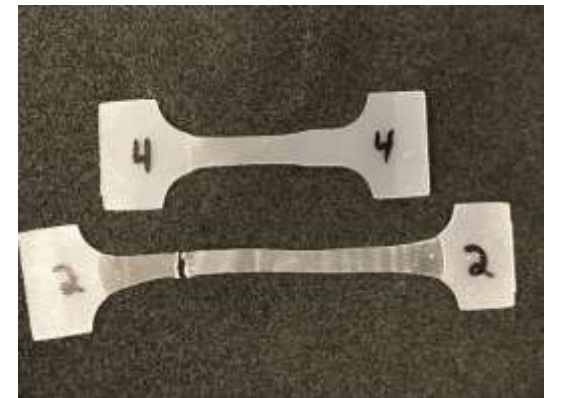
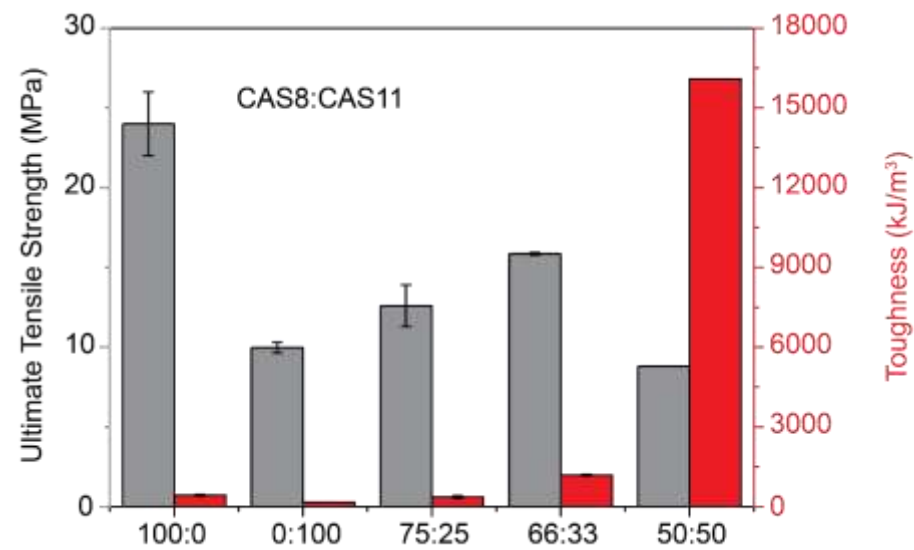
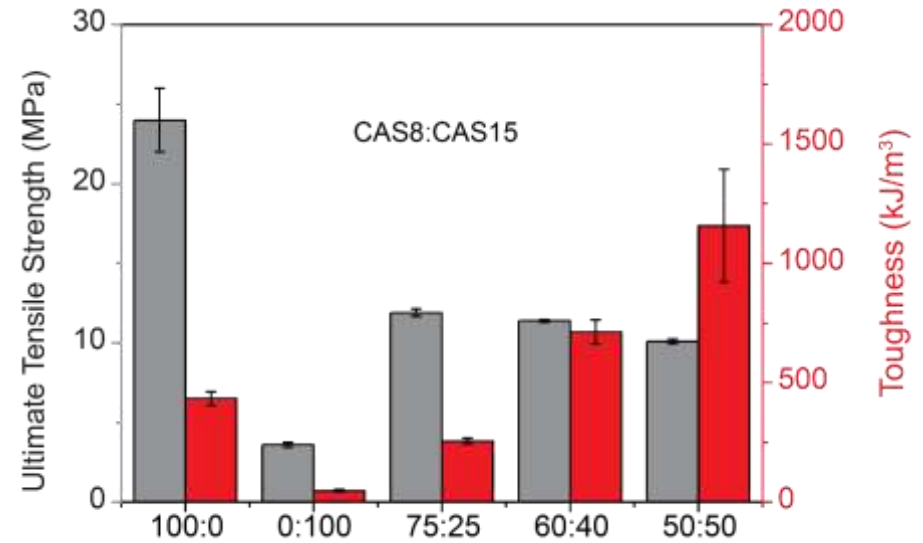
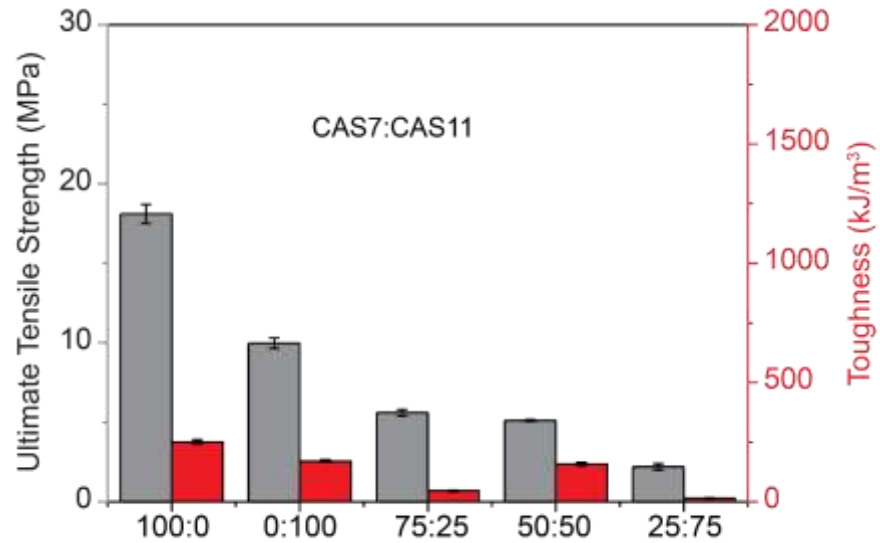
# Ring-Opening Copolymers

Anionic ring-opening copolymerization of  $\epsilon$ -caprolactam (CL) with  $\omega$ -laurolactam (LL)

- More flexible chains
- Lower crystallinity



# Mechanical Properties



50:50 CAS8:CAS11

# Acknowledgements



Scott Polymer Dojo

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- ARC Discovery Project DP210100901